



## Material Content Data Sheet



<b>Sales Product Name</b>				IPB180N10S4-02		<b>Issued</b>		20. July 2018	
<b>MA#</b>				MA001074084					
<b>Package</b>				PG-TO263-7-3		<b>Weight*</b>		1542.16 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	12.330	0.80	0.80	7996	7996	
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		521		
	inorganic material	phosphorus	7723-14-0	0.241	0.02		156		
	non noble metal	copper	7440-50-8	801.714	51.99	52.06	519862	520540	
wire	non noble metal	aluminium	7429-90-5	132.798	8.61	8.61	86111	86111	
encapsulation	organic material	carbon black	1333-86-4	7.014	0.45		4548		
	plastics	epoxy resin	-	77.151	5.00		50028		
	inorganic material	silicondioxide	60676-86-0	383.417	24.86	30.31	248623	303199	
leadfinish	non noble metal	tin	7440-31-5	12.317	0.80	0.80	7987	7987	
plating	non noble metal	nickel	7440-02-0	0.269	0.02		175		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	1	175	
solder	noble metal	silver	7440-22-4	0.194	0.01		126		
	non noble metal	tin	7440-31-5	0.155	0.01		101		
	non noble metal	lead	7439-92-1	7.409	0.48	0.50	4804	5031	
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		69		
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21		
	non noble metal	copper	7440-50-8	106.210	6.89	6.90	68871	68961	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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